



Notes: (Unless Otherwise Specified)

- 1) DIE MATERIAL IS SILICON
- 2) DIE THICKNESS 250~750um (10~30MIL) OPTIONAL
- 3) METALLIZATION
 - Layer 1: 300A Ti
 - Layer 2: 1.0um ALUMINUM (Al)
- 4) FILM OXIDE: SiO₂ (3000A)
- 5) APPLICATION: WIRE BONDING

PAD LOCATIONS:
 Row 1 Outer Row
 Row 2 Middle Row
 Row 3 Inner Row

TOLERANCE UNLESS NOTED		APPROVALS	DATE	TopLine®			
X.XX	± 0.01						
X.XXX	± 0.005	DRAWN J. HINES	2/26/2011				
X.XXXX	± 0.0005	ENG		SCALE 100:1			
ANGLES	± 0.5°	MFG					
ALL DIMENSIONS IN		QA		DRAWING NO. 700380			
<input checked="" type="checkbox"/> INCHES <input type="checkbox"/> MILLIMETERS		CUST					
THIRD ANGLE PROJECTION		REVISED		DO NOT SCALE DRAWING			